

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claim 1 (currently amended) An electroless plating A method of manufacturing a wiring substrate, comprising the steps of:

preparing a substrate having an insulating body and a conductive pattern having electrodes formed on the insulating body, the electrodes on which connection pads of an electronic part are connected;

adhering a catalytic metal serving as a catalyst of an electroless plating onto the insulating body and the conductive pattern;

coating selectively an oxidizing agent, which can oxidize the catalytic metal and make the catalytic metal in an inactive state to the electroless plating, on the catalytic metal in a space portion between the electrodes of the conductive pattern; and

forming selectively a metal layer on the conductive pattern by the electroless plating, wherein the conductive pattern is arranged in a state such that the space portion distance between the electrodes of the conductive pattern in the space portion between the electrodes has a plurality of different values dimensions, the oxidizing agent is selectively coated in the space portions which are smaller than 30  $\mu$ m, thereby, the step of forming a solder resist pattern on the

~~space portion is omitted by forming [[and]] the oxidizing agent is selectively coated in portions, which are smaller than both a predetermined dimension and the space portion, out of the space portion between the electrodes of the conductive pattern.~~

Claim 2 (canceled).

Claim 3 (previously presented) An electroless plating method according to claim 1, wherein the step of selectively coating the oxidizing agent is carried out by an ink jet method.

Claim 4 (original) An electroless plating method according to claim 1, wherein the step of adhering the catalytic metal onto the insulating body and the conductive pattern includes the step of coating an activating solution containing ions of the catalytic metal to deposit the catalytic metal by an oxidation-reduction reaction.

Claims 5-6 (canceled).

Claim 7 (original) An electroless plating method according to claim 1, wherein the catalytic metal is palladium, and the metal layer formed by the electroless plating is a nickel layer or a copper layer.

Claim 8 (canceled).

Claim 9 (previously presented) An electroless plating method according to claim 11, wherein the protection film is a resist film or a polyimide film.

Claim 10 (previously presented) An electroless plating method according to claim 1, wherein the oxidizing agent is one of an  $H_2SO_4$  solution and a mixed solution consisting of  $H_2SO_4$  and HC1.

Claim 11 (currently amended) ~~An electroless plating~~ A method of manufacturing a wiring substrate, comprising the steps of:

preparing a substrate having an insulating body and a conductive pattern having electrodes formed on the insulating body, the electrodes on which connection pads of an electronic part are connected;

adhering a catalytic metal serving as a catalyst of an electroless plating onto the insulating body and the conductive pattern;

forming selectively a protection film on the catalytic metal in a space portion between the conductive pattern; and

forming selectively a metal layer on the conductive pattern by the electroless plating, wherein the conductive pattern is arranged such that the space portion distance between electrodes of the conductive patterns pattern in the space portion between the electrodes has a plurality of different values-dimensions, the oxidizing agent is selectively coated in the space

portions which are smaller than 30  $\mu\text{m}$ , thereby, the step of forming a solder resist pattern on the space portion is omitted by forming the oxidized agent and the protection film is formed selectively in portions, which are smaller than both a predetermined dimension and the space portion, out of the space portion between the electrodes of the conductive pattern.

Claim 12 (canceled).